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TITLE: NI-880XS	DOCUMENT NO: 98ASA00325D REV: A	
	STANDARD: NON-JEDEC	
	SOT1790-1 23 FEB 2016	



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION H IS MEASURED .030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.905	-.915	22.99	-23.24	U	-	-.040	-	-1.02
B	.380	-.390	9.65	-9.91	Z	-	-.030	-	-0.76
C	.125	-.170	3.18	-4.32	aaa	-	.005	-	0.127
D	.595	-.605	15.11	-15.37	bbb	-	.010	-	0.254
E	.035	-.045	0.89	-1.14	ccc	-	.015	-	0.381
F	.003	-.006	0.08	-0.15	-	-	-	-	-
H	.057	-.067	1.45	-1.70	-	-	-	-	-
K	.170	-.210	4.32	-5.33	-	-	-	-	-
M	.872	-.888	22.15	-22.56	-	-	-	-	-
N	.871	-.889	22.12	-22.58	-	-	-	-	-
R	.365	-.375	9.27	-9.53	-	-	-	-	-
S	.365	-.375	9.27	-9.53	-	-	-	-	-

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